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Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2004 [Approved on 30 January 2015, 15:09 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.40000%	Nickel	7440-02-0	1.00000%
			Gold	7440-57-5	11.50000%
			Polydimethyl siloxane	63148-62-9	25.00000%
			Silicon	7440-21-3	62.50000%
Die attach	Lead and Lead alloys	2.10000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	16.70000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE	1309-64-4	0.80000%
			Tetrabromobisphenol A (TBBPA)	79-94-7	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz sand	60676-86-0	70.30000%
Leadfinish	Tin plating	6.80000%	Copper	7440-50-8	0.80000%
			Silver	7440-22-4	3.70000%
			Tin	7440-31-5	95.50000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	71.00000%	Nickel	8049-31-8	0.40000%
			Copper	7440-50-8	99.60000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-213AB/MELF	Diode SMD	0.12	g